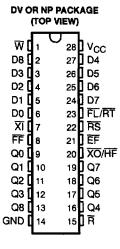
SN74ACT7200L, SN74ACT7201LA, SN74ACT7202LA 256 × 9, 512 × 9, 1024 × 9 ASYNCHRONOUS FIRST-IN, FIRST-OUT MEMORIES SCAS221A- FEBRUARY 1993 - REVISED SEPTEMBER 1995

- Reads and Writes Can Be Asynchronous or Coincident
- Organization:
 - SN74ACT7200L 256 × 9
 - SN74ACT7201LA 512 × 9
 - SN74ACT7202LA 1024 × 9
- Fast Data Access Times of 15 ns
- Read and Write Frequencies up to 40 MHz
- Bit-Width and Word-Depth Expansion
- Fully Compatible With the IDT7200/7201/7202
- Retransmit Capability
- Empty, Full, and Half-Full Flags
- TTL-Compatible inputs
- Available in 28-Pin Plastic DIP (NP),
 Small-Outline (DV), and 32-Pin Plastic
 J-Leaded Chip-Carrier (RJ) Packages

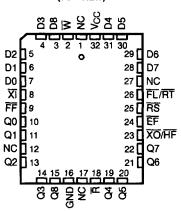
description

The SN74ACT7200L, SN74ACT7201LA, and SN74ACT7202LA are constructed with dual-port SRAM and have internal write and read address counters to provide data throughput on a first-in, first-out (FIFO) basis. Write and read operations are independent and can be asynchronous or coincident. Empty and full status flags prevent underflow and overflow of memory, and depth-expansion logic allows combining the storage cells of two or more devices into one FIFO. Word-width expansion is also possible.

Data is loaded into memory by the write-enable (\overline{W}) input and unloaded by the read-enable (\overline{R}) input. Read and write cycle times of 25 ns (40 MHz) are possible with data access times of 15 ns.



RJ PACKAGE (TOP VIEW)

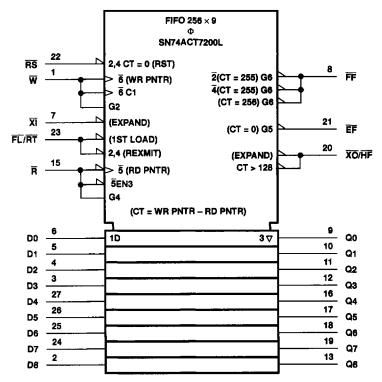


NC - No internal connection

These devices are particularly suited for providing a data channel between two buses operating at asynchronous rates. Applications include use as rate buffers from analog-to-digital converters in data-acquisition systems, temporary storage elements between buses and magnetic or optical memories, and queues for communication systems. A 9-bit-wide data path is provided for the transmission of byte data plus a parity bit or packet-framing information. The read pointer can be reset independently of the write pointer for retransmitting previously read data when a device is not used in depth expansion.

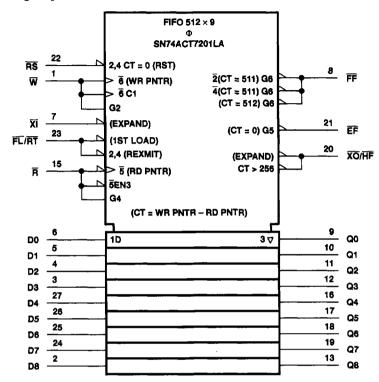
The SN74ACT7200L, SN74ACT7201LA, and SN74ACT7202LA are characterized for operation from 0°C to 70°C.

SN74ACT7200L logic symbol[†]



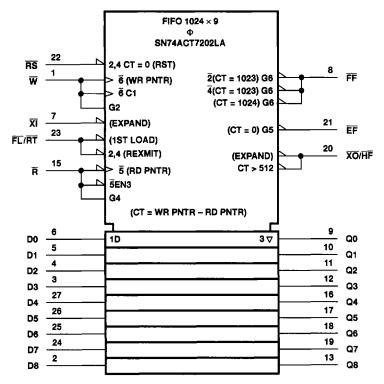
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DV and NP packages.

SN74ACT7201LA logic symbol[†]



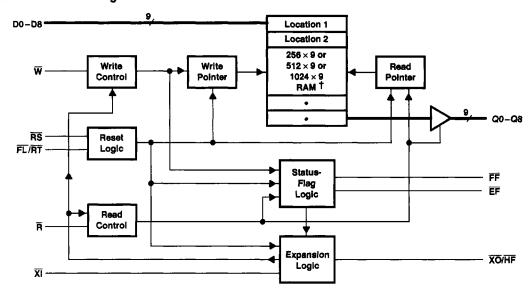
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DV and NP packages.

SN74ACT7202LA logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DV and NP packages.

functional block diagram



^{†256 × 9} for SN74ACT7200L; 512 × 9 for SN74ACT7201LA; 1024 × 9 for SN74ACT7202LA

RESET AND RETRANSMIT FUNCTION TABLE (single-device depth; single-or multiple-device width)

INPUTS		INTERNAL	(OUTPU'	TS	PULICATION		
RS	FLIRT	Χī	READ POINTER	R WRITE POINTER EF FF		FF	XO/HF	FUNCTION
L	Х	L	Location zero	Location zero	L	Н	H	Reset device
н	L	L	Location zero	Unchanged	Х	Х	х	Retransmit
Н	Н	L	Increment if EF high	Increment if FF high	Х	Х	Х	Read/write

RESET AND FIRST-LOAD FUNCTION TABLE (multiple-device depth; single-or multiple-device width)

INPUTS			INTERNAL	OUT	PUTS	FUNCTION	
RS	FL/RT	ΧĪ	READ POINTER	WRITE POINTER	ĒF	FF	FUNCTION
L	L	‡	Location zero	Location zero	L	Н	Reset first device
L	н	‡	Location zero	Location zero	L	н	Reset all other devices
н	Х	#	X	x	Х	X	Read/write

[‡] XI is connected to XO/HF of the previous device in the daisy chain (see Figure 15).

Terminal Functions

TERMINAL NAME	1/0	DESCRIPTION
D0-D8	1	Data inputs
EF	0	Empty-flag output. $\overline{E}F$ is low when the read pointer is equal to the write pointer, inhibiting any operation initiated by a read cycle. When the FIFO is empty, a data word can be read automatically at Q0-Q8 by holding \overline{R} low when loading the data word with a low-level pulse on \overline{W} .
FF	0	Full-flag output. \overline{FF} is low when the write pointer is one location less than the read pointer, indicating that the device is full and inhibiting any operation initiated by a write cycle. \overline{FF} goes low when the number of writes after reset exceeds the number of reads by 256 for the SN74ACT7200L, 512 for the SN74ACT7201LA, and 1024 for the SN74ACT7202LA. When the FIFO is full, a data word can be written automatically into memory by holding \overline{W} low while reading out another data word with a low-level pulse on \overline{R} .
		First-load/retransmit input. FL/RT performs two separate functions. When cascading two or more devices for word-depth expansion, FL/RT is tied to ground on the first device in the daisy chain to indicate that it is the first device loaded and unloaded; it is tied high on all other devices in the depth-expansion chain.
FE/RT	ı	A device is not used in depth expansion when its expansion (\overline{XI}) input is tied to ground. In that case, $\overline{FL/RT}$ acts as a retransmit enable. A retransmit operation is initiated when $\overline{FL/RT}$ is pulsed low. This sets the internal read pointer to the first location and does not affect the write pointer. \overline{R} and \overline{W} must be at a high logic level during the low-level $\overline{FL/RT}$ retransmit pulse. Retransmit should be used only when less than 256/512/1024 writes are performed between resets; otherwise, an attempt to retransmit can cause the loss of unread data. The retransmit function can affect $\overline{XO/HF}$ depending on the relative locations of the read and write pointers.
GND		Ground
Q0-Q8	0	Data outputs. Q0 – Q8 are in the high-impedance state when \overline{R} is high or the FIFO is empty.
R	ı	Read-enable input. A read cycle begins on the falling edge of \overline{R} if \overline{EF} is high. This activates Q0 – Q8 and shifts the next data value to this bus. The data outputs return to the high-impedance state as \overline{R} goes high. As the last stored word is read by the falling edge of \overline{R} , \overline{EF} transitions low but Q0 – Q8 remain active until \overline{R} returns high. When the FIFO is empty, the internal read pointer is unchanged by a pulse on \overline{R} .
RS	1	Reset input. A reset is performed by taking \overline{RS} low. This initializes the internal read and write pointers to the first location and sets \overline{EF} low, \overline{FF} high, and \overline{HF} high. Both \overline{R} and \overline{W} must be held high for a reset during the window shown in Figure 7. A reset is required after power up before a write operation can take place.
Vcc		Supply voltage
W	I	Write-enable input. A write cycle begins on the falling edge of \overline{W} if \overline{FF} is high. The value on D0 – D8 is stored in memory as \overline{W} returns high. When the FIFO is full, \overline{FF} is low, inhibiting \overline{W} from performing any operation on the device.
ΧI	ı	Expansion-in input. \overline{XI} performs two functions. \overline{XI} is tied to ground to indicate that the device is not used in depth expansion. When the device is used in depth expansion, \overline{XI} is connected to the expansion-out (\overline{XO}) output of the previous device in the depth-expansion chain.
XO/HF	0	Expansion-out/half-full-flag output. $\overline{XO}/H\overline{F}$ performs two functions. When the device is not used in depth expansion (i.e., when \overline{XI} is tied to ground), $\overline{XO}/H\overline{F}$ indicates when half the memory locations are filled. After half of the memory is filled, the falling edge on \overline{W} for the next write operation drives $\overline{XO}/H\overline{F}$ low. $\overline{XO}/H\overline{F}$ remains low until a rising edge of \overline{R} reduces the number of words stored to exactly half of the total memory.
		When the device is used in depth expansion, XO/HF is connected to XI of the next device in the daisy chain. XO/HF drives the daisy chain by sending a pulse to the next device when the previous device reaches the last memory location.



SN74ACT7200L, SN74ACT7201LA, SN74ACT7202LA 256 × 9, 512 × 9, 1024 × 9 ASYNCHRONOUS FIRST-IN, FIRST-OUT MEMORIES SCAS221A - FEBRUARY 1993 - REVISED SEPTEMBER 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} (see Note 1)	***************************************	-0.5 V to 7 V
Input voltage range (any input), V ₁		-0.5 V to 7 V

Voltage applied to a disabled 3-state outp	ut	5.5 V
Operating free-air temperature range, TA		. 0°C to 70°C

recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	٧
ViH	1 link laveline Aveldere	प्रा	2.6			V
	High-level input voltage	Other inputs	2			V
v_{IL}	Low-level input voltage				0.8	V
ЮН	High-level output current				-2	mA
lOL	Low-level output current				8	mA
TA	Operating free-air temperature		0		70	°C

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 5.5 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	_	MIN	TYP	MAX	UNIT
VOH	V _{CC} = 4.5 V,	I _{OH} ≈ − 2 mA		2.4			٧
VOL	V _{CC} = 4.5 V,	IOL = 8 mA				0.4	>
lozij	VO = VCC	ਜੋ≥V _{IH}				±10	μА
lozl	V _O = 0.4 V,	R≥VIH				±10	μА
1)	V _I = 0 to 5.5 V			-1		1	μА
	t _a = 15 and 25 ns				125 [¶]	mA	
lcc1 [‡]	ta = 35 and 50 ns			50	80	IIIA	
	ta = 15 and 25 ns			15	4		
ICC2‡	t _a = 35 and 50 ns	R, W, RS, and FL/RT at	VIH		5	8	mA
1+	t _a = 15 and 25 ns	V- V 00V					
lcc3 [‡]	ta = 35 and 50 ns	V _I = V _{CC} - 0.2 V				0.5	mA
Ci§	$V_{\parallel} = 0$,	T _A = 25°C,	f = 1 MHz			8	pF
C _o §	V _O = 0,	T _A = 25°C,	f = 1 MHz			8	pF

[‡] i_{CC1} = supply current; I_{CC2} = standby current; I_{CC3} = power-down current. I_{CC} measurements are made with outputs open (only capacitive loading).



[†] S:resses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND.

[§] This parameter is sampled and not 100% tested.

[¶] Tested at fclock = 20 MHz

SN74ACT7200L, SN74ACT7201LA, SN74ACT7202LA 256 \times 9, 512 \times 9, 1024 \times 9 ASYNCHRONOUS FIRST-IN, FIRST-OUT MEMORIES SCAS221A - FEBRUARY 1983 - REVISED SEPTEMBER 1986

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

		FIGURE ACT7202		01LA-15	5 'ACT7201LA-25			1LA-35† 12LA-35†	'ACT72 'ACT72 'ACT72	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	1
f _{clock}	Clock frequency, R or W			40		28.5		22.2		15	MHz
t _{c(R)}	Cycle time, read	1(a)	25		35		45		65		ns
t _{c(W)}	Cycle time, write	1(b)	25		35		45		65		ns
t _{c(RS)}	Cycle time, reset	7	25	_	35		45		65		ns
t _{c(RT)}	Cycle time, retransmit	4	25		35		45		65		ns
tw(RL)	Pulse duration, R low	1(a)	15		25		35		50		ns
tw(WL)	Pulse duration, W low	1(b)	15		25		35		50		ns
tw(RH)	Pulse duration, R high	1(a)	10		10		10		15		ns
tw(WH)	Pulse duration, W high	1(b)	10		10		10		15		ns
tw(RT)	Pulse duration, FL/RT low	4	15		25		35		50		ns
tw(RS)	Pulse duration, RS low	7	15		25		35		50		ns
tw(XIL)	Pulse duration, XI low	10	15		25		35		50		ns
tw(XIH)	Pulse duration, XI high	10	10		10		10		10		ns
tsu(D)	Setup time, data before W↑	1(b), 6	11		15		18		30		ns
t _{su(RT)}	Setup time, R and W high before FL/RT1‡	4	15	_	25		35	_	50		ns
t _{su} (RS)	Setup time, R and W high before RS↑‡	7	15		25		35		50		ns
tsu(XI-R)	Setup time, XI low before R↓	10	10		10		10		15		ns
tsu(XI-W)	Setup time, XI low before W↓	10	10		10		10		15		ns
th(D)	Hold time, data after W↑	1(b), 6	0	-	0		0		5		ns
th(E-R)	Hold time, R low after EF↑	5, 11	15		25		35		50		ns
th(F-W)	Hold time, W low after FF↑	6, 12	15		25		35		50		ns
th(RT)	Hold time, R and W high after FL/RT↑	4	10		10		10		15		ns
th(RS)	Hold time, R and W high after RS↑	7	10		10		10		15		ns

[†] Released in RJ package only

[‡] These values are characterized but not currently tested.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (see Figure 13)

PARAMETER		FIGURE	'ACT72	'ACT7200L-15 'ACT7201LA-15 'ACT7202LA-15		'ACT7200L-25 'ACT7201LA-25 'ACT7202LA-25		'ACT7201LA-35† 'ACT7202LA-35†		'ACT7200L-50 'ACT7201LA-50 'ACT7202LA-50	
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	1
ta	Access time, R↓ or EF↑ to data out valid	1(a), 3, 5		15		25		35		50	пѕ
^t v(RH)	Valid time, data out valid after R↑	1(a)	5		5		5		5		ns
ten(R-QX)	Enable time, R to Q outputs at low impedance‡	1(a)	5		5		10		10		ns
ter (W-QX)	Enable time, WT to Q outputs at low impedance‡§	5	5	<u> </u>	5		5		15		ns
^t dis(R)	Disable time, R↑ to Q outputs at high impedance‡	1(a)		15		18		20		30	ns
^t w(FH)	Pulse duration, FF high in automatic write mode	6		15		25		30		45	ns
^t w(EH)	Pulse duration, EF high in automatic read mode	5		15		25		30		45	ns
^t pd(W-F)	Propagation delay time, W↓ to FF low	2		15		25		30		45	ns
^t pd(R-F)	Propagation delay time, Rî to FF high	2, 6, 12		15		25		30	; !	45	ns
^t pd(RS-F)	Propagation delay time, RSJ to FF high	7		25		35		45		65	ns
^t pd(RS-HF)	Propagation delay time, RS↓ to XO/HF high	7		25		35		45		65	ns
(a-W)cq ^t	Propagation delay time, W↑ to EF high	3, 5, 11		15		25		30		45	ns
^t pd(R-E)	Propagation delay time, R↓ to EF low	3		15		25	_	30		45	ns
^t pd(RS-E)	Propagation delay time, RS↓ to EF low	7		25	l	35		45		65	ns
^t pd(W-HF)	Propagation delay time, W↓ to XO/HF low	8		25		35		45		65	ns
^t pd(R-HF)	Propagation delay time, R↑ to XO/HF high	8		25		35		45		65	ns
^t rd(R-XOL)	Propagation delay time, R↓ to XO/HF low	9		15		25		35		50	ns
^t pd(W-XOL)	Propagation delay time, W↓ to XO/HF low	9		15		25		35		50	ns
^t pd(R-XOH)	Propagation delay time, R↑ to XO/HF high	9		15		25		35		50	ns
^t pd(W-XOH)	Propagation delay time, W↑ to XO/HF high	9		15		25		35		50	ns
^t pd(RT-FL)	Propagation delay time, FL/RT↓ to HF, EF, FF valid	4		25		35		45		65	ns

[†] Released in RJ package only

[‡] These values are characterized but not currently tested.

[§] Only applies when data is automatically read (see Figure 5)

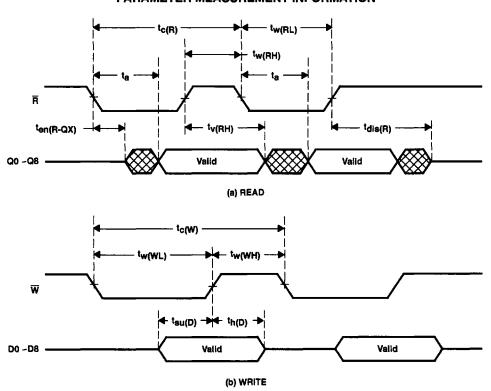


Figure 1. Asynchronous Waveforms

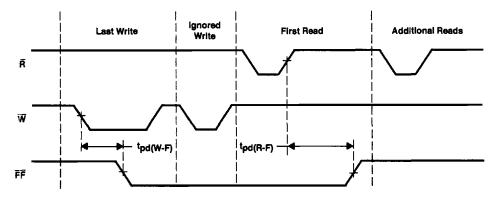


Figure 2. Full-Flag Waveforms

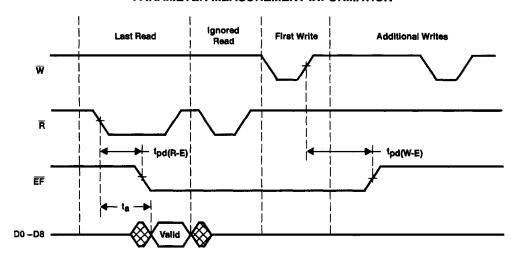
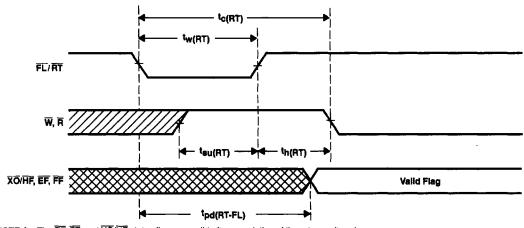


Figure 3. Empty-Flag Waveforms



NOTE A: The EF, FF, and XO/HF status flags are valid after completion of the retransmit cycle.

Figure 4. Retransmit Waveforms



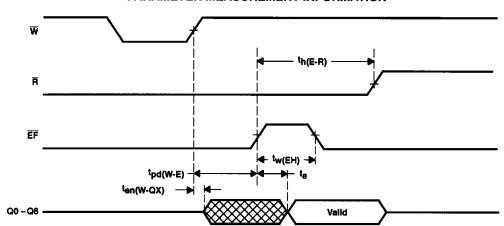


Figure 5. Automatic-Read Waveforms

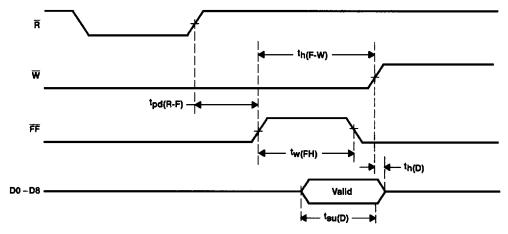


Figure 6. Automatic-Write Waveforms

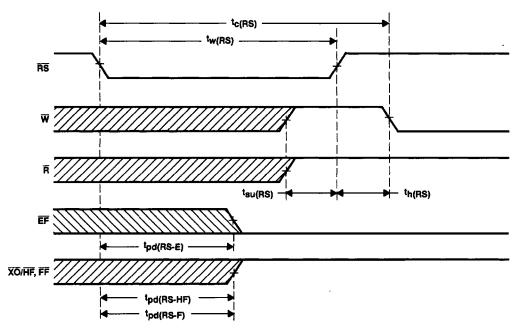


Figure 7. Master-Reset Waveforms

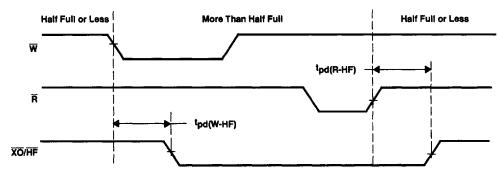


Figure 8. Half-Full Flag Waveforms

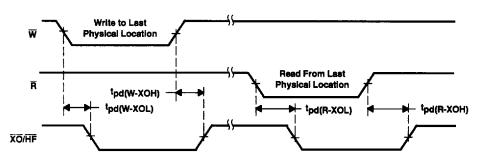


Figure 9. Expansion-Out Waveforms

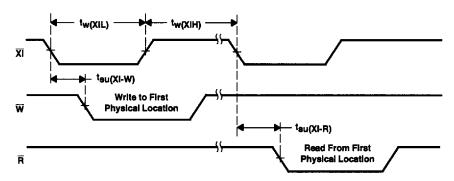


Figure 10. Expansion-In Waveforms

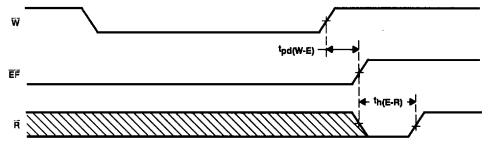


Figure 11. Minimum Timing for an Empty-Fiag Coincident-Read Pulse

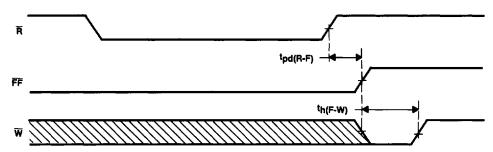
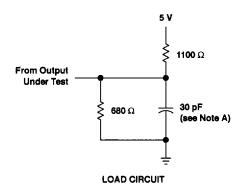


Figure 12. Minimum Timing for a Full-Flag Coincident-Write Pulse

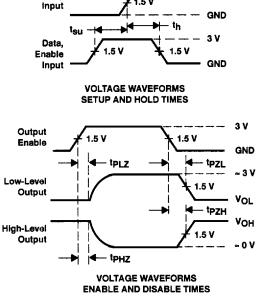
SCAS221A - FEBRUARY 1993 - REVISED SEPTEMBER 1995

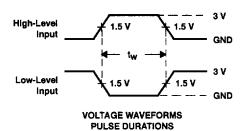
Timing

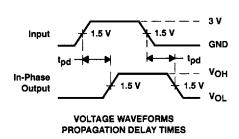
PARAMETER MEASUREMENT INFORMATION



3 V







NOTE A Includes probe and jig capacitance

Figure 13. Load Circuit and Voltage Waveforms

Combining two or more devices to create one FIFO with a greater number of memory bits is accomplished in two different ways. Width expansion increases the number of bits in each word by connecting FIFOs with the same depth in parallel. Depth expansion uses the built-in expansion logic to daisy-chain two or more devices for applications requiring more than 256, 512, or 1024 words of storage. Width expansion and depth expansion can be used together.

width expansion

Word-width expansion is achieved by connecting the corresponding input control to multiple devices with the same depth. Status flags (\overline{EF} , \overline{FF} , and \overline{HF}) can be monitored from any one device. Figure 14 shows two FIFOs in a width-expansion configuration. Both devices have their expansion-in (\overline{XI}) inputs tied to ground. This disables the depth-expansion function of the device, allowing the first-load/retransmit ($\overline{FL/RT}$) input to function as a retransmit (\overline{RT}) input and the expansion-out/half-full ($\overline{XO/HF}$) output to function as a half-full (\overline{HF}) flag.

depth expansion

The SN74ACT7200L/7201LA/7202LA is easily expanded in depth. Figure 15 shows the connections used to depth expand three SN74ACT7200L/7201LA/7202LA devices. Any depth can be attained by adding additional devices to the chain. The SN74ACT7200L/7201LA/7202LA operates in depth expansion under the following conditions:

- The first device in the chain is designated by tying FL to ground.
- All other devices must have their FL inputs at a high logic level.
- XO of each device must be tied to XI of the next device.
- External logic is needed to generate a composite FF and EF. All FF outputs must be ORed together and all EF outputs must be ORed together.
- RT and HF functions are not available in the depth-expanded configuration.

combined depth and width expansion

Both expansion techniques can be used together to increase depth and width. This is done by first creating depth-expanded units and then connecting them in a width-expanded configuration (see Figure 16).

SN74ACT7200L/7201LA/7202LA

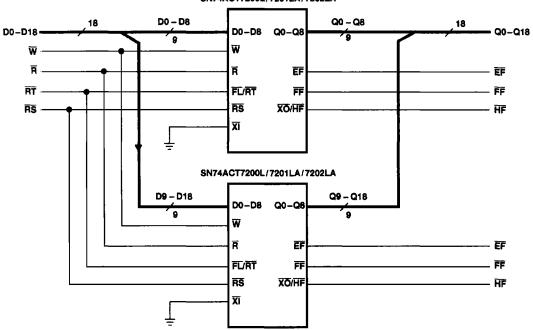


Figure 14. Word-Width Expansion: 256/512/1024 Words × 18 Bits

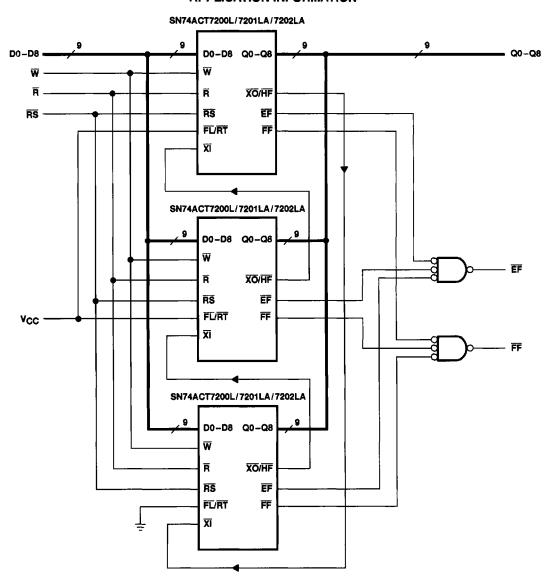


Figure 15. Word-Depth Expansion: 768/1536/3072 Words \times 9 Bits

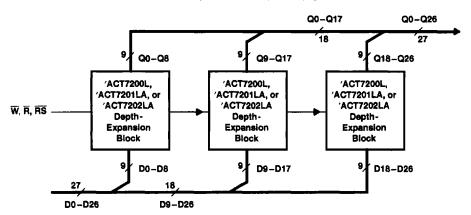


Figure 16. Word-Depth Plus Word-Width Expansion